

Advanced Power MOSFET

SSR/U3055A

FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 10 μA (Max.) @ $V_{DS} = 60\text{V}$
- Lower $R_{DS(on)}$: 0.097 Ω (Typ.)

$BV_{DSS} = 60\text{ V}$
 $R_{DS(on)} = 0.15\ \Omega$
 $I_D = 8\text{ A}$

D-PAK I-PAK



1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	60	V
I_D	Continuous Drain Current ($T_c=25^\circ\text{C}$)	8	A
	Continuous Drain Current ($T_c=100^\circ\text{C}$)	5	
I_{DM}	Drain Current-Pulsed	32	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy	55	mJ
I_{AR}	Avalanche Current	8	A
E_{AR}	Repetitive Avalanche Energy	1.8	mJ
dv/dt	Peak Diode Recovery dv/dt	5.5	V/ns
P_D	Total Power Dissipation ($T_A=25^\circ\text{C}$) *	2.5	W
	Total Power Dissipation ($T_c=25^\circ\text{C}$)	18	W
	Linear Derating Factor	0.14	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	7.04	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient *	--	50	
$R_{\theta JA}$	Junction-to-Ambient	--	110	

* When mounted on the minimum pad size recommended (PCB Mount).

SAMSUNG
ELECTRONICS

SSR/U3055A

N-CHANNEL
POWER MOSFET

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	60	--	--	V	$V_{GS}=0\text{V}, I_D=250\ \mu\text{A}$
$\Delta BV/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.060	--	$\text{V}/^\circ\text{C}$	$I_D=250\ \mu\text{A}$ See Fig 7
$V_{GS(\text{th})}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{DS}=5\text{V}, I_D=250\ \mu\text{A}$
I_{GSS}	Gate-Source Leakage , Forward	--	--	100	nA	$V_{GS}=20\text{V}$
	Gate-Source Leakage , Reverse	--	--	-100		$V_{GS}=-20\text{V}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	10	μA	$V_{DS}=60\text{V}$
		--	--	100		$V_{DS}=48\text{V}, T_C=125\ ^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-State Resistance	--	--	0.15	Ω	$V_{GS}=10\text{V}, I_D=4\text{A}$ ④
g_{fs}	Forward Transconductance	--	6.17	--	S	$V_{DS}=30\text{V}, I_D=4\text{A}$ ④
C_{iss}	Input Capacitance	--	280	360	pF	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	110	125		
C_{rss}	Reverse Transfer Capacitance	--	40	46		
$t_{d(on)}$	Turn-On Delay Time	--	11	25	ns	$V_{DD}=30\text{V}, I_D=10\text{A}, R_G=24\ \Omega$ See Fig 13 ④ ⑤
t_r	Rise Time	--	17	40		
$t_{d(off)}$	Turn-Off Delay Time	--	27	60		
t_f	Fall Time	--	28	60		
Q_g	Total Gate Charge	--	12	17	nC	$V_{DS}=48\text{V}, V_{GS}=10\text{V}, I_D=10\text{A}$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	--	2.4	--		
Q_{gd}	Gate-Drain(" Miller ") Charge	--	5.4	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_s	Continuous Source Current	--	--	8	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	32	A	
V_{SD}	Diode Forward Voltage ④	--	--	1.5	V	$T_J=25^\circ\text{C}, I_S=8\text{A}, V_{GS}=0\text{V}$
t_{rr}	Reverse Recovery Time	--	55	--	ns	$T_J=25^\circ\text{C}, I_F=10\text{A}$
Q_{rr}	Reverse Recovery Charge	--	0.11	--	μC	$dI_F/dt=100\text{A}/\mu\text{s}$ ④

Notes :

① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature

② $L=1\text{mH}, I_{AS}=8\text{A}, V_{DD}=25\text{V}, R_G=27\ \Omega$, Starting $T_J=25\ ^\circ\text{C}$

③ $I_{SD} \leq 10\text{A}, dI/dt \leq 200\text{A}/\mu\text{s}, V_{DD} \leq V_{DSS}$, Starting $T_J=25\ ^\circ\text{C}$

④ Pulse Test : Pulse Width = $250\ \mu\text{s}$, Duty Cycle $\leq 2\%$

⑤ Essentially Independent of Operating Temperature

N-CHANNEL POWER MOSFET

SSR/U3055A

Fig 1. Output Characteristics

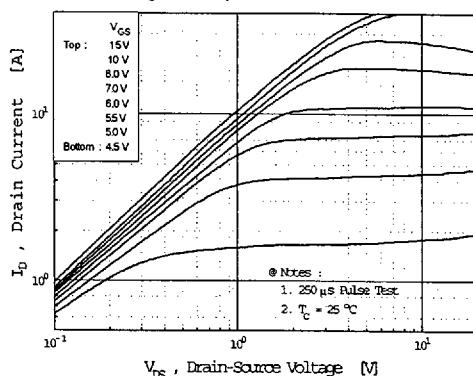


Fig 2. Transfer Characteristics

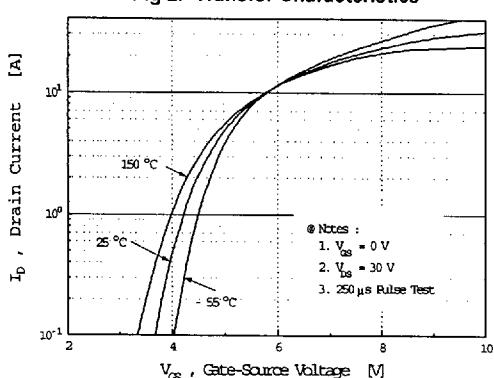


Fig 3. On-Resistance vs. Drain Current

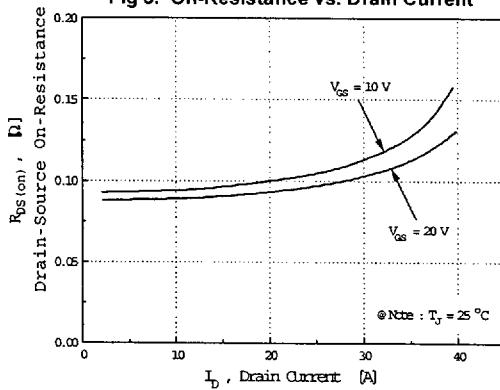


Fig 4. Source-Drain Diode Forward Voltage

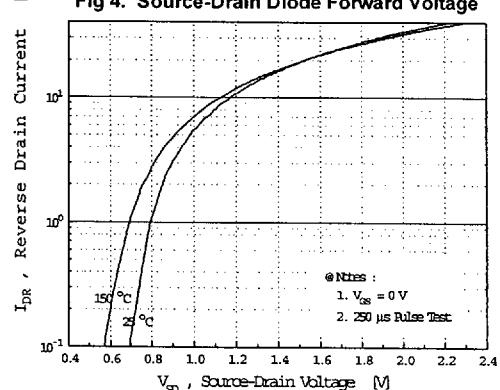


Fig 5. Capacitance vs. Drain-Source Voltage

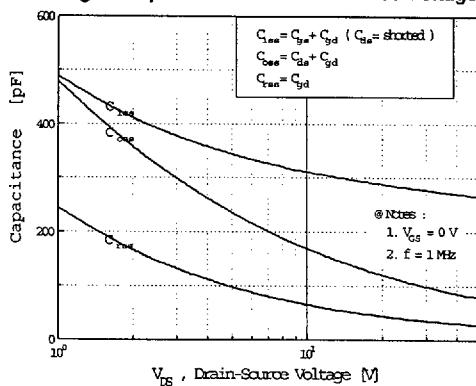
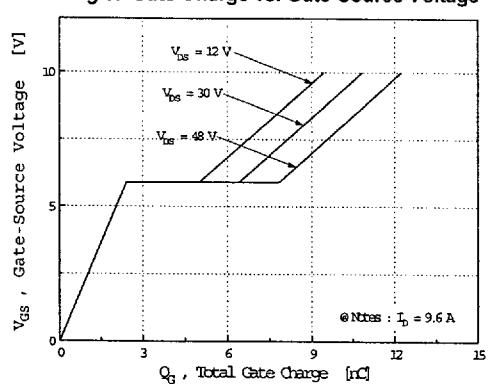
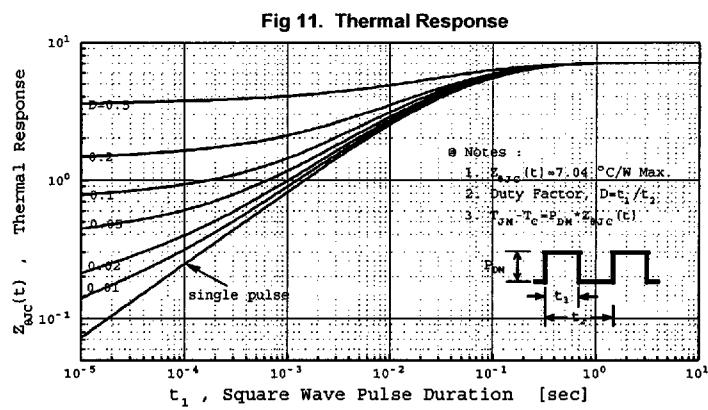
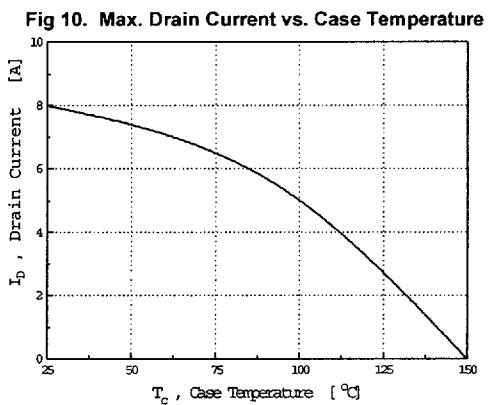
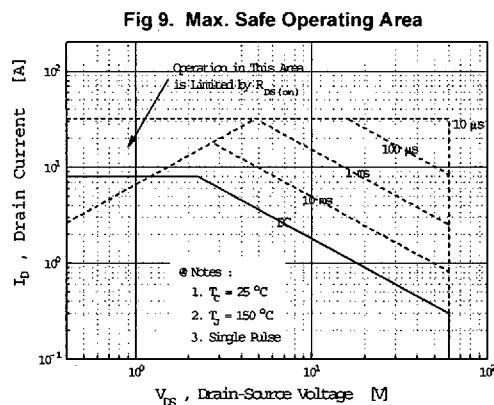
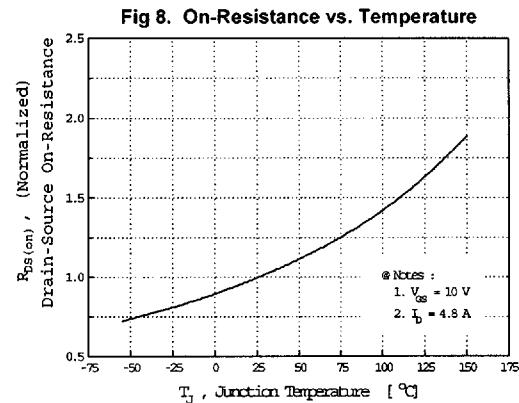
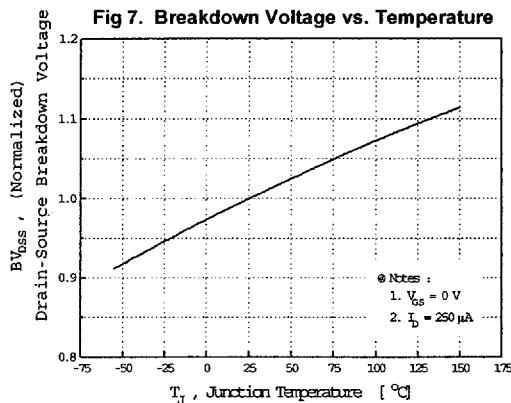


Fig 6. Gate Charge vs. Gate-Source Voltage



SSR/U3055A

N-CHANNEL
POWER MOSFET



N-CHANNEL
POWER MOSFET

SSR/U3055A

Fig 12. Gate Charge Test Circuit & Waveform

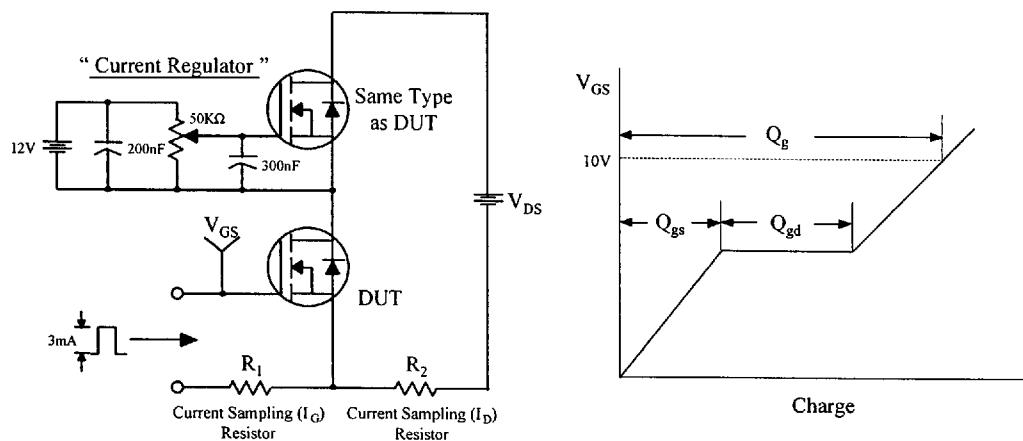


Fig 13. Resistive Switching Test Circuit & Waveforms

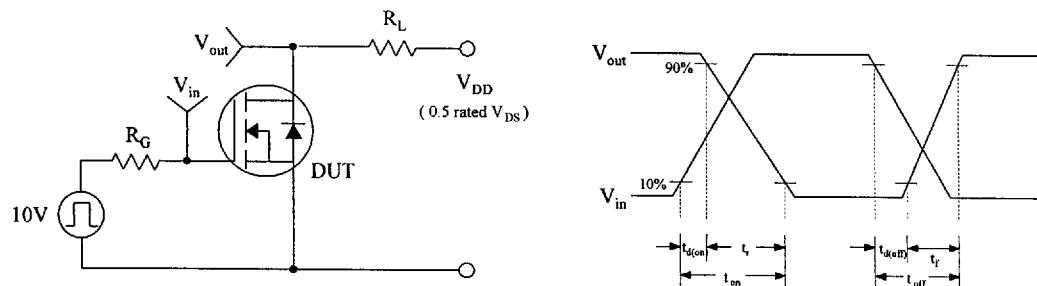
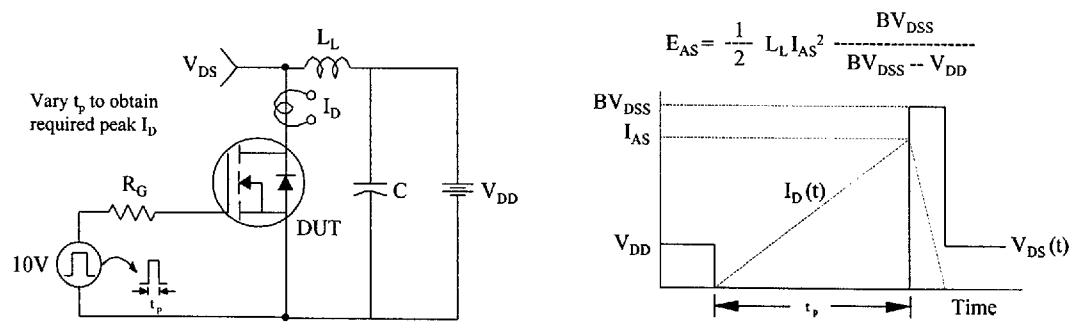


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



SSR/U3055A

N-CHANNEL
POWER MOSFET

Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

